



AVBUU-UZ7-A15

1P65 MILTARY ICELAKE D-2733NT, TOTAL 50GBE, DUAL 25GSFP, DUAL GPU SERVER







- Design to meet MIL-810, MIL-461 EMC/EMI.
- Intel® Xeon D-2733NT 8 cores 2.1GHz Max Turbo 3.2GHz.
- Dual Nvidia RTX A4500 5888 CUDA cores PCle Gen 4.0 x16.
- 2x25GbESFP28LAN Port + 2xRJ45 10 GbE base-T ports.
- M.2 NVMe 2TB (R/W, 7150/5250 MB/sec)
- U.3 NVMe 64TB x 2.
- Hardware Secure Erase(AES) button, Swappable CMOS battery
- Extreme Temperature -20~60C
- Size: 405 x 316 x 195 mm.
- IP65 Sealed with External Cooling Blade
- MIL-STD-810G Thermal, Shock, Vibration, Humidity
- Power 18V~36V DC Input

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1. INTRODUCTION '

Artificial intelligence (AI) is quickly becoming one of the most crucial elements of business success.

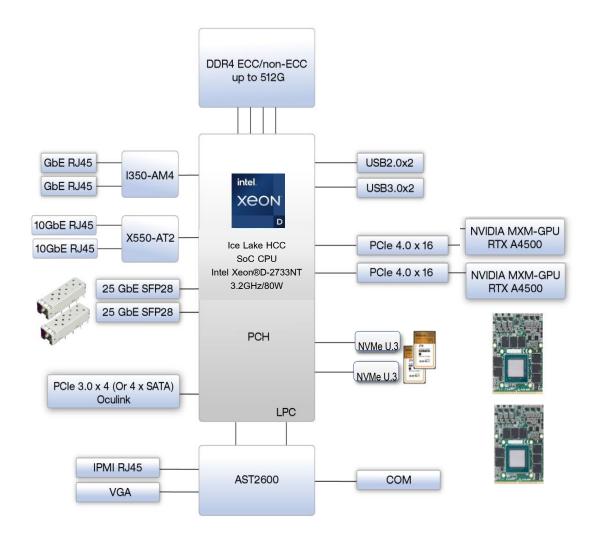
Today, deploying powerful computing platforms that can accelerate and scale their AI-based products and services while adapting them to harsh environments has become vital for many successful military applications.



7Starlake is innovating to address the emerging high-throughput inference market driven by IoT devices which are generating huge amounts of data. The combination of NVIDIA CUDA parallel Processor cores and the new architecture-based GeForce Accelerator is an ideal combination for demanding and latency-sensitive workloads.

2.MAIN FEATURE

- Ultra High Performance Intel® Xeon Ice Lake-D, D-2733NT (8xCores)
- NVIDIA MXM-GPU Quadro RTX A4500 5888 CUDA x2
- MIL-STD 810 Thermal, Vibration, Shock, Humidity
- 2 x 25GbE SFP28, 2x10GbE RJ45, 4 x1GbE RJ45
- Up to 512GB LRDIMM/256GB RDIMM,
- 2 x NVMe PCle Gen 4.0 U.3, 1 x NVMe PCle Gen4 M.2.
- Dual Removable Anti-Drop Solid-State Disk
- Hardware Secure Erase (AES) by option
- IP65 Sealed with External Cooling Blade
- MIL-STD-810G Thermal, Shock, Vibration, Humidity
- MIL-STD 461 EMI/EMC
- Power 18V~36V DC-IN
- Extreme Temperature Support -20~+60°C



3.MIL-STD Environment

- Operating Temperature High: 50°C, MIL-STD-810G, Method 501.5, Procedure I.
- Operating Temp Low: 0°C, MIL-STD-810G, Method502.5, Procedure I.
- Non-Operating Temperature High: 70°C, MIL-STD-810G, Method 501.5, Procedure II.
- Non-Operating Temperature Low:-40°C, MIL-STD-810G, Method 502.5, Procedure II.
- Operating Altitude: Up to 15,000ft., MIL-STD-810G, Method 500.5.
- Non-Operating Altitude: Up to 45,000ft., MIL-STD-810G, Method 500.5.
- Humidity: MIL-STD-810G, Method 507.5., Procedure Ib(Natural Cycle B3)
- Shock: MIL-STD-810G,Method 516.6, 30g's,Saw-tooth, 11ms & MIL-DTL-901E Grade A., Class II., Type B.
- Vibration: MIL-STD-167, Type I, Deck Mounted Equipment.
- EMI/EMC: MIL-STD-461F, RE101, RE102, (Shipboard Level 1), RS103, CE101, CE102, CS101, CS114, CS116.
- Airborne Noise: MIL-STD-740-1 compliance: 43.7dBA (Idle), 52.5dBA(50%), 54.6dBA(80%)

4.SYSTEM SPEC

System

CPU	Intel® Xeon® D-2733NT, 8 core, 16 thread, 15MB Cache, 2.1GHz Max Turbo up	
	to 3.2GHz. Single socket FCBGA-2579, up to 80W TDP。	
Memory type	256GB RDIMM ECC DDR4-2666/2400 MHz,	
	512G LRDIMM DDR4-2666/2400MHz in 4 DIMM Slot	
Chipset	Intel® SoC Integrated	
GPU	2 x NVidia® RTX A4500, 5888 CUDA Cores, PCIe Gen4.0 x16	
Display	VGA, Resolution up to 1920x1200@60Hz 32bpp	
Chipset	Aspeed AST2600 BMC	
Ethernet Controller	Dual LAN with 25G SFP28 LAN via SoC	
	Dual LAN with 10G LAN via Intel® X550	
	Quad LAN with Gigabit LAN via Intel®i350	
LAN	4 x 1GBase-T, 2 x 10GBase-T LAN, 2 x 25GBase SFP-	
Storage	2 x 2TB, 2.5" SSD hot-swap, with AES function	
	1 x 256GB, NVMe M.2 2280 by PCIe	
Power Type	18V~36V DC Input	
Dimension	405mm x 316mm x 195mm (W x L x H)	
Front I/O		
XO	1 x USB3.0 Amphenol USB3FTV7AZNF312 connector	
X1	1 x 1GBase-T TV07RW-13-98S connector	
X2	1 x 1GBase-T TV07RW-13-98S connector	
Х3	1 x 1GBase-T TV07RW-13-98S connector	
X4	1 x 1GBase-TTV07RW-13-98S connector	
X5	DC In connector	
X6	1 x 10GBase-T M20 RJ45 CAT6A connector	
X7	1 x 10GBase-T M20 RJ45 CAT6A connector	
X8	1 x 25G Fiber Ethernet Amphenol FSI MPOFTV70ZNN	
X9	1 x 25G Fiber Ethernet Amphenol FSI MPOFTV70ZNN	
VGA	D-sub 15 connector with waterproof cap	

Environmental

Environmental			
MIL-STD-810 Test	Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia) Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature & Humidity) Method 509.7 Salt Spray (50±5)g/L Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 4,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration) Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)		
Reliability	Conduction Cooling. Designed & Manufactured using ISO 9001 Certified Quality Program.		
	CE102 basic curve, 10kHz - 30 MHz		
	RE102-4, (1.5 MHz) -30 MHz - 5 GHz		
	RS103, 200 MHz - 3.2 GHz, 50 V/m equal for all frequencies		
MIL-STD-461	EN 61000-4-2: Air discharge: 8 kV, Contact discharge: 6kV		
WILE STD 401	EN 61000-4-3: 10V/m, EN 61000-4-4: Signal and DC-Net: 1 kV		
	EN 61000-4-5: Leads vs. ground potential 1kV, Signal und DC-Net: 0.5 kV		
	CE and FCC		
MIL-STD-1275	Steady State – 20V~33V, Surge Low – 18V/500ms, Surge High – 100V/500ms Emitted spikes Injected Voltage surges Emitted voltage surges Voltage ripple (2V) Voltage spikes Starting Operation Reverse polarity		
Operating Temp.	-20 to +60°C		
Storage Temp.	-40 to +85°C		
Relative Humidity	5% to 95%, non-condensing.		
Operating System			
Operating System	Windows 10 64Bit, Linux by option		
RoHS	RoHS compliant		
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5.DIMENSION





6.Ordering Information

Model	AV800-D27-A45	PER800-D27	
Туре	Rugged	Industrial	
CPU	Intel Xeon D-2733NT		
Memory	256GB RDIMM ECC DDR4-2666/2400 MHz		
GPU	2 x MXM embedded NVIDIA RTX™ A4500		
RAM	Up to 256G DDR4 RDIMM 2666/2400MHz		
Storage	M.2 (2TB) and 2 x SATA III (16TB) U.3		
NIC	2 x 25GbE SPF + 2 x 10GbE + 4 x GbE + IPMI		
Power	18V~36V DC Input		
Dimension	405 x 316 x 195mm (W x D x H)	416 x 301 x 106 mm(W x D x H)	